## SN54174, SN54175, SN54LS174, SN54LS175, SN54S174, SN54S175, SN74174, SN74175, SN74LS174, SN74LS175, SN74S174, SN74S175 HEX/QUADRUPLE D-TYPE FLIP-FLOPS WITH CLEAR

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'174, 'LS174, 'S174 . . . HEX D-TYPE FLIP-FLOPS '175, 'LS175, 'S175 . . . QUADRUPLE D-TYPE FLIP-FLOPS

- '174, 'LS174, 'S174 Contain Six Flip-Flops with Single-Rail Outputs
- '175, 'LS175, 'S175 Contain Four Flip-Flops with Double-Rail Outputs
- Three Performance Ranges Offered: See Table Lower Right
- Buffered Clock and Direct Clear Inputs
- Individual Data Input to Each Flip-Flop
- Applications include: Buffer/Storage Registers Shift Registers

Pattern Generators

#### description

These monolithic, positive-edge-triggered flip-flops utilize TTL circuitry to implement D-type flip-flop logic. All have a direct clear input, and the '175, 'LS175, and 'S175 feature complementary outputs from each flipflop.

Information at the D inputs meeting the setup time requirements is transferred to the Q outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going pulse. When the clock input is at either the high or low level, the D input signal has no effect at the output.

These circuits are fully compatible for use with most TTL circuits.

FUNCTION TABLE												
(EACH FLIP-FLOP)												
	NPUTS		ουτ	PUTS								
CLEAR	CLOCK	D	٩	ā۲								
L L	x	х	L	н								
н	1	н	н	L								
н	1	L	L	н								
н	L	х	a <sub>0</sub>	₫ <sub>0</sub>								

H = high level (steady state)

L = low level (steady state)

X = irrelevant

t = transition from low to high level

 $\Omega_0$  = the level of  $\Omega$  before the indicated steady-state

input conditions were established. † = '175, 'LS175, and 'S175 only

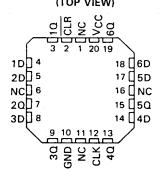
	TYPICAL	TYPICAL
TYPES	MAXIMUM	POWER
TTFES	CLOCK	DISSIPATION
	FREQUENCY	PER FLIP-FLOP
'174, '175	35 MHz	38 mW
'LS174, 'LS175	40 MHz	14 mW
'S174, 'S175	110 MHz	75 mW

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

SN54174, SN54LS174, SN54S174 J OR W PACKAGE
SN74174 N PACKAGE
SN74LS174, SN74S174, D OR N PACKAGE

(TOP VIEW) 10 2 15 60 1D 🛛 3 14 🗌 6D 13 0 5D 2D 4 20 5 12 50 3D 🗌 6 11 🗌 4D 30 07 10 40 GND 8 9 CLK

SN54LS174, SN54S174 . . . FK PACKAGE (TOP VIEW)

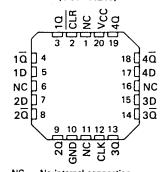


SN54175, SN54LS175, SN54S175...J OR W PACKAGE SN74175...N PACKAGE

SN74LS175, SN74S175...D OR N PACKAGE (TOP VIEW)

•		•
	hτ	
10[	2	15 40
١āĽ	3	14 🛛 40
1 D 🗌	4	13 🗍 4 D
2 D 🗌	5	12 🗍 3 D
2 <u>0</u> [	6	11]] 30
20	]7	10 🛛 30.
GND	8	9 СLК

#### SN54LS175, SN54S175 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

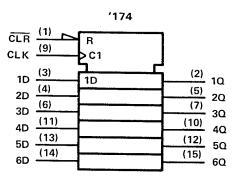
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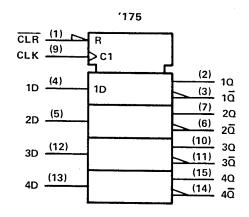
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# SN54174, SN54175, SN54LS174, SN54LS175, SN54S174, SN54S175, SN74174, SN74175, SN74LS174, SN74LS175, SN74S174, SN74S175 HEX/QUADRUPLE D-TYPE FLIP-FLOPS WITH CLEAR

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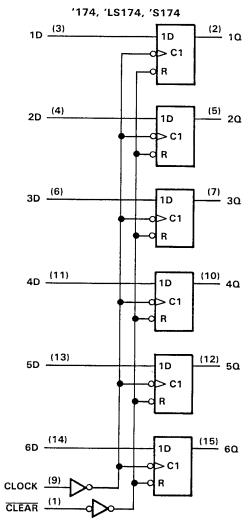
logic symbols<sup>†</sup>





<sup>†</sup>These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

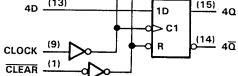
## logic diagrams (positive logic)



1D <u>(4)</u> <u>(2)</u> 10 1D > C1<u>(3)</u> 10 R (7) 20 (5) 2D 1D > C1 <u>(6)</u> 20 R 3D (12) (10) 30 1D ⊳cı <u>(11)</u> 30 R (15) 40 4D (13) 1D

'175, 'LS175, 'S175

۰.



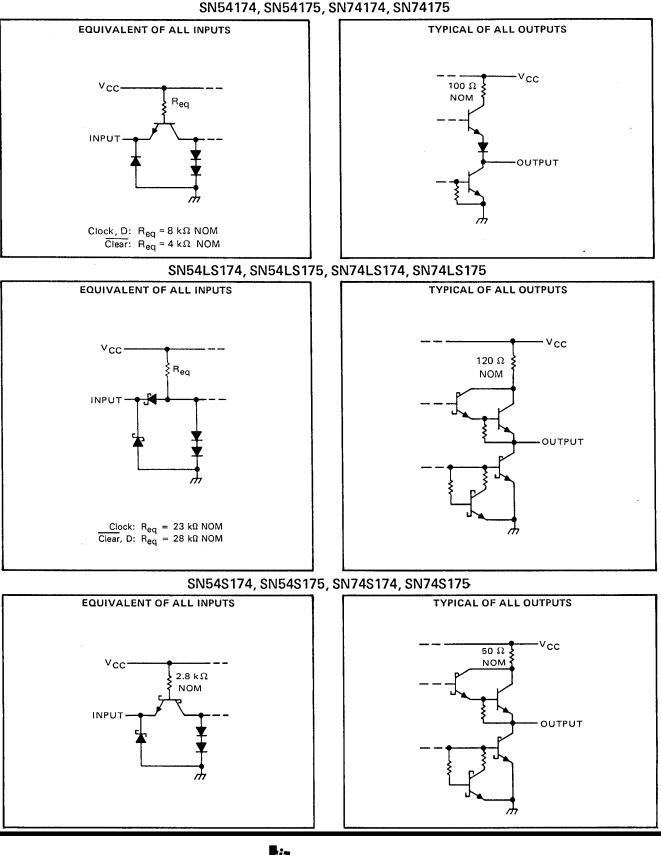
Pin numbers shown are for D, J, N, and W packages.



## SN54174, SN54175, SN54LS174, SN54LS175, SN54S174, SN54S175, SN74174, SN74175, SN74LS174, SN74LS175, SN74S174, SN74S175 **HEX/QUADRUPLE D-TYPE FLIP-FLOPS WITH CLEAR**

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schematics of inputs and outputs





# SN54174, SN54175, SN74174, SN74175 HEX/QUADRUPLE D-TYPE FLIP-FLOPS WITH CLEAR

absolute maximum ratings over operating free-air temperature ratio	ange (unless otherwise noted)
Supply voltage, V <sub>CC</sub> (see Note 1)	
Input voltage	
Operating free-air temperature range: SN54174, SN54175 Circuits	
SN74174, SN74175 Circuits	$\ldots$ $\ldots$ $\ldots$ $\ldots$ $\ldots$ $\ldots$ $\ldots$ $\ldots$ $0^{\circ}$ C to $70^{\circ}$ C
Storage temperature range	$-65^{\circ}C$ to $150^{\circ}C$

NOTE 1: Voltage values are with respect to network ground terminal.

## recommended operating conditions

		SN54	174, SN	54175	SN74	SN74174, SN74175			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Supply voltage, V <sub>CC</sub>		4.5	5	5.5	4.75	5	5.25	V	
High-level output current, IOH				-800			-800	μA	
Low-level output current, IOL				16	[		16	mA	
Clock frequency, fclock		0		25	0		25	MHz	
Width of clock or clear pulse, tw		20			20			ns	
Cotum time t	Data input	20			20			ns	
Setup time, t <sub>su</sub>	Clear inactive-state	25			25			ns	
Data hold time, t <sub>h</sub>		5			5			ns	
Operating free-air temperature, TA		-55		125	0		70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIC	NS <sup>†</sup>	MIN	<b>ΤΥΡ</b> ‡	MAX	UNIT
VIH	High-level input voltage			2			V
VIL	Low-level input voltage					0.8	V
VIK	Input clamp voltage	$V_{CC} = MIN, I_I = -12$	mA			-1.5	V
V <sub>ОН</sub>	High-level output voltage	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V <sub>IL</sub> = 0.8 V, I <sub>OH</sub> = -		2.4	3.4		v
VOL	Low-level output voltage	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V <sub>IL</sub> = 0.8 V, I <sub>OL</sub> = 16			0.2	0.4	v
-μ	Input current at maximum input voltage	V <sub>CC</sub> = MAX, V <sub>1</sub> = 5.5	V			1	mA
Чн	High-level input current	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.4	V			40	μA
կլ	Low-level input current	$V_{CC} = MAX, V_I = 0.4$	V			-1.6	mA
1.			SN54'	-20		-57	
los	Short-circuit output current §	V <sub>CC</sub> = MAX	SN74'	-18		-57	mA
1	Current		2 '174		45	65	
1CC	Supply current	V <sub>CC</sub> = MAX, See Note	2 /175		30	45	mA

<sup>†</sup>For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable device type.

<sup>‡</sup>All typical values are at  $V_{CC}$  = 5 V,  $T_A$  = 25°C.

\$ Not more than one output should be shorted at a time.

NOTE 2: With all outputs open and 4.5 V applied to all data and clear inputs, I<sub>CC</sub> is measured after a momentary ground, then 4.5 V, is applied to clock.

## switching characteristics, $V_{CC} = 5 V$ , $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	MIN	ТҮР	MAX	UNIT
f <sub>max</sub>	Maximum clock frequency		25	35		MHz
	Propagation delay time, low-to-high-level output from clear			16 23	25	
<sup>t</sup> PLH	(SN54175, SN74175 only)	$C_L = 15  \text{pF},$			25	ns
<sup>t</sup> PHL	Propagation delay time, high-to-low-level output from clear	R <sub>L</sub> = 400 Ω, See Note 3			35	ns
<sup>t</sup> PLH	Propagation delay time, low-to-high-level output from clock	See Note 3		20	30	ns
<sup>t</sup> PHL	Propagation delay time, high-to-low-level output from clock			24	35	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



# SN54LS174, SN54LS175, SN74LS174, SN74LS175 HEX/QUADRUPLE D-TYPE FLIP-FLOPS WITH CLEAR

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absolute maximum ratings over operating free-air temperature range	(un	le	SS	ot	he	rw	ise	e n	101	tec	1)			÷	
Supply voltage, V <sub>CC</sub> (see Note 1)		•						•			•		•	•	7 V
Input voltage															
Operating free-air temperature range: SN54LS174, SN54LS175 Circuits							•		•			-55	5°C	c to	125°C
SN74LS174, SN74LS175 Circuits			. '										$0^{\circ}$	'C to	o 70°C
Storage temperature range		•	•	•	•	•	•	•	•	•		-65	5°C	C to	150°C

NOTE 1: Voltage values are with respect to network ground terminal.

#### recommended operating conditions

		SN	154LS1	74	SN	UNIT		
		SI	<b>V54LS1</b>	75	SN			
		MIŅ	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V <sub>CC</sub>		4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH				-400			-400	μA
Low-level output current, IOL	······································			4			8	mA
Clock frequency, fclock		0		30	0		30	MHz
Width of clock or clear pulse, t <sub>w</sub>		20			20			ns
Sotup time t	Data input	20			20			ns
Setup time, t <sub>su</sub>	Clear inactive-state	25			25			ns
Data hold time, th		5			5			ns
Operating free-air temperature, TA		-55		125	0		70	°C

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS <sup>†</sup>			-	N54LS1 N54LS1		S S	UNIT		
		1			MIN	TYP‡	MAX	MIN	TYP‡	MAX	
VIH	High-level input voltage				2			2		~~~	V
VIL	Low-level input voltage						0.7			0.8	V
٧ <sub>IK</sub>	Input clamp voltage	V <sub>CC</sub> = MIN,	l <sub>1</sub> = -18 mA				-1.5			-1.5	V
v <sub>он</sub>	High-level output voltage	V <sub>CC</sub> = MIN, V <sub>IL</sub> = V <sub>IL</sub> max	V <sub>IH</sub> = 2 V, I <sub>OH</sub> = -400 μA	λ	2.5	3.5		2.7	3.5		v
Vol	Low-level output voltage	V <sub>CC</sub> = MIN, V <sub>IL</sub> = V <sub>IL</sub> max		IOL = 4 mA		0.25	0.4		0.25 0.35	0.4	V
łı	Input current at maximum input voltage	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 7 V				0.1			0.1	mA
Чн	High-level input current	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 2.7 V				20			20	μA
կլ	Low-level input current	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 0.4 V		1		-0.4			-0.4	mA
los	Short-circuit output current §	V <sub>CC</sub> = MAX			-20		100	-20		-100	mA
Icc	Supply current	Vcc = MAX,	See Note 2	'LS174		16	26		16	26	mA
			VCC - WAX, See Note 2 'L			11	18		11	18	

<sup>1</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

 $\ddagger$ All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

\$Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

NOTE 2: With all outputs open and 4.5 V applied to all data and clear inputs, I<sub>CC</sub> is measured after a momentary ground, then 4.5 V, is applied to clock.

## switching characteristics, $V_{CC}$ = 5 V, $T_A$ = 25°C

PABAMETER	TEST CONDITIONS		'LS174		'LS175			
FANAMETEN	TEST CONDITIONS	MIN	түр	MAX	MIN	түр	MAX	UNIT
f <sub>max</sub> Maximum clock frequency		30	40		30	40		MHz
tPLH Propagation delay time, low-to-high-level output from clear	C <sub>L</sub> = 15 pF,					20	30	ns
tpHL Propagation delay time, high-to-low-level output from clear	$R_{\rm L} = 2  k \Omega$ ,		23	35	t	20	30	ns
tPLH Propagation delay time, low-to-high-level output from clock	See Note 3		20	30		13	25	ns
tphL Propagation delay time, high-to-low-level output from clock	1		21	30		16	25	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



# SN54S174, SN54S175, SN74S174, SN74S175 HEX/QUADRUPLE D-TYPE FLIP-FLOPS WITH CLEAR

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#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V <sub>CC</sub> (see Note 1)	7 V
Input voltage	5.5 V
Operating free-air temperature range: SN54S174, SN54S175 Circuits	$55^{\circ}C$ to $125^{\circ}C$
SN74S174, SN74S175 Circuits	$ 0^{\circ}$ C to 70°C
Storage temperature range	

NOTE 1: Voltage values are with respect to network ground terminal.

## recommended operating conditions

		SN545	5174, SN	54S175	SN74S	174, SN	74S175	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V <sub>CC</sub>		4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH				-1			-1	mA
Low-level output current, IOL			20			20	mA	
Clock frequency, fclock		0		75	0		75	MHz
Pulso width t	Clock	7			7			
Pulse width, t <sub>w</sub>	Clear	10			10			ns
Satura tima t	Data input	5			5			
Setup time, t <sub>su</sub>	Clear inactive-state	5			5			ns
Data hold time, t <sub>h</sub>	3			3			ns	
Operating free-air temperature, T <sub>A</sub>				125	0		70	°C

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS <sup>†</sup>		MIN	түр‡	MAX	UNIT
VIH	High-level input voltage			2			V
VIL	Low-level input voltage					0.8	V
VIK	Input clamp voltage	$V_{CC} = MIN, I_I = -18 \text{ mA}$				-1.2	V
		$V_{CC} = MIN, V_{IH} = 2V,$	SN54S'	2.5	3.4		v
VOH	VOH High-level output voltage	V <sub>IL</sub> = 0.8 V, I <sub>OH</sub> = -1 mA	2.7	3.4			
M		$V_{CC} = MIN, V_{IH} = 2 V,$	• • • • • • • • • • • • • • • • • • •			0.5	V
VOL	Low-level output voltage	V <sub>IL</sub> = 0.8 V, I <sub>OL</sub> = 20 mA			0.5	v	
lj –	Input current at maximum input voltage	V <sub>CC</sub> = MAX, V <sub>I</sub> = 5.5 V				1	mA
ЧΗ	High-level input current	V <sub>CC</sub> = MAX, V <sub>1</sub> = 2.7 V				50	μA
ΊL	Low-level input current	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.5 V				-2	mA
los	Short-circuit output current §	V <sub>CC</sub> = MAX		-40		-100	mA
1	Supply support	No MAX - See Note 2	'174		90	144	
<sup>I</sup> CC	Supply current	V <sub>CC</sub> = MAX, See Note 2	<b>'17</b> 5		60	96	mA

<sup>†</sup>For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable device type.

<sup>‡</sup>All typical values are at  $V_{CC} = 5 V$ ,  $T_A = 25^{\circ}C$ . <sup>§</sup>Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

NOTE 2: With all outputs open and 4.5 V applied to all data and clear inputs, ICC is measured after a momentary ground, then 4.5 V, is applied to clock.

## switching characteristics, $V_{CC} = 5 V$ , $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	MIN	түр	MAX	UNIT
f <sub>max</sub>	Maximum clock frequency		75	110		MHz
₽LH	Propagation delay time, low-to-high-level $\overline{\Omega}$ output from clear (SN54S175, SN74S175 only)	С <sub>L</sub> = 15 рF,		10	15	ns
t₽HL	Propagation delay time, high-to-low-level Q output from clear	$R_{L} = 280 \Omega,$ See Note 3		13	22	ns
<sup>t</sup> PLH	Propagation delay time, low-to-high-level output from clock	See Note 3		8	12	ns
<sup>t</sup> PHL	Propagation time, high-to-low-level output from clock			11.5	17	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.





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## **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	n MSL Peak Temp <sup>(3)</sup>
JM38510/01702BEA	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
JM38510/01702BFA	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI
JM38510/07105BEA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/07105BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
JM38510/07106BEA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/30106B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30106BEA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/30106BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
JM38510/30107B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30107BEA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/30107BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
JM38510/30107SEA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/30107SFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SN54175J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN54LS174J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS175J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN54S174J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN54S175J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN74174N	OBSOLETE	PDIP	Ν	16		TBD	Call TI	Call TI
SN74175N	OBSOLETE	PDIP	Ν	16		TBD	Call TI	Call TI
SN74175N3	OBSOLETE	PDIP	Ν	16		TBD	Call TI	Call TI
SN74LS174D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS174DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS174DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS174DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS174DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS174DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS174J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN74LS174N	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS174N3	OBSOLETE	PDIP	Ν	16		TBD	Call TI	Call TI
SN74LS174NE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS174NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS174NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS174NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

# PACKAGE OPTION ADDENDUM

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Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp
SN74LS175D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS175DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS175DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS175DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS175DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
SN74LS175DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
SN74LS175J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN74LS175N	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS175N3	OBSOLETE	PDIP	Ν	16		TBD	Call TI	Call TI
SN74LS175NE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS175NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
SN74LS175NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
SN74LS175NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
SN74S174J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN74S174N	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S174N3	OBSOLETE	PDIP	Ν	16		TBD	Call TI	Call TI
SN74S174NE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S174NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
SN74S174NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
SN74S174NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)		Level-1-260C-UNLI
SN74S175D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
SN74S175DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
SN74S175DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
SN74S175DR	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI
SN74S175N	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S175N3	OBSOLETE	PDIP	Ν	16		TBD	Call TI	Call TI
SN74S175NE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S175NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI

18-Sep-2008

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74S175NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S175NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54175J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SNJ54175W	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI
SNJ54LS174FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS174J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS174W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS175FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS175J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS175W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54S174FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S174J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54S174W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54S175FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S175J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54S175W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

www ti com

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

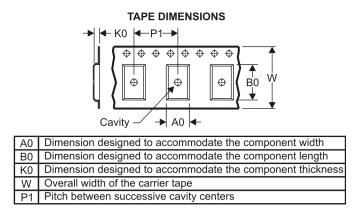
<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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## TAPE AND REEL INFORMATION





# QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

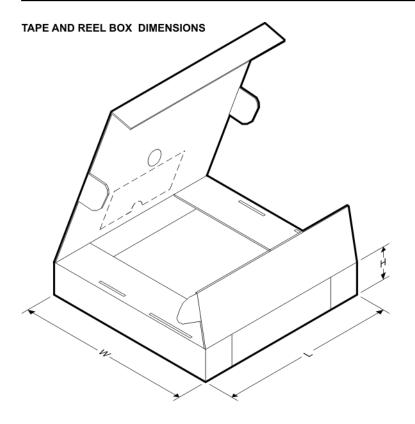


*All dimensions are nominal												
Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS174DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS174NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LS175DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS175NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74S174NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74S175NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1



# PACKAGE MATERIALS INFORMATION

19-Mar-2008



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS174DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS174NSR	SO	NS	16	2000	346.0	346.0	33.0
SN74LS175DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS175NSR	SO	NS	16	2000	346.0	346.0	33.0
SN74S174NSR	SO	NS	16	2000	346.0	346.0	33.0
SN74S175NSR	SO	NS	16	2000	346.0	346.0	33.0

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